

IN THE SPECIFICATION:

Please amend the paragraph [0053] as follows:

[0053] Output terminal OSI of CCD chip 11 and input terminal 65 of buffer amplifier module 61 are connected via a bonding wire 68. Output terminal 67 of buffer amplifier module 61 is connected via a bonding wire 69 to a predetermined package side electrode OS2. Terminal OD is connected via a bonding wire 71 to a terminal 72 of buffer amplifier module 61 and is electrically connected to terminal 70. Terminal 70 is connected via a bonding wire 47 [[74]] to a predetermined package side electrode.